

Claims

1. A method of manufacturing a sealed module that houses a circuit board supporting one more electronic components, the method comprising the steps of:

mechanically and electrically attaching an electrical connector to a first
5 end of the circuit board;

providing a housing open at only one end, said housing having an inner periphery shaped to accommodate said circuit board and said electrical connector;

orienting said housing with said one end facing upward, and dispensing
10 a first quantity of potting material into said housing through said one end;

inserting said circuit board and attached electrical connector into the one end of said housing such that only a marginal portion of said circuit board including a second end of said circuit board opposite said first end is immersed into said first quantity of potting material;

15 sealing said electrical connector to the inner periphery of said housing;
and

curing said first quantity of potting material to secure said circuit board to the inner periphery of said housing.

2. The method of Claim 1, where said marginal portion of said circuit board is free of said electronic components so that said first quantity of potting material does not come into contact with said components.

3. The method of Claim 1, including the steps of:

dispensing a second quantity of potting material onto an outboard surface of said connector; and

curing said second quantity of potting material to seal said electrical
5 connector to the inner periphery of said housing.

4. The method of Claim 3, including the steps of:

- providing a base plate on said electrical connector that conforms to the inner periphery of said housing so as to create a pocket defined by said base plate and the inner periphery of said housing when said circuit board and
- 5 attached electrical connector are inserted into the one end of said housing; and
- dispensing said second quantity of potting material into said pocket.